

*Concluded  
S1  
A1*

an external connecting terminal electrically connected to the active surface of the semiconductor chip and projecting therefrom.

2. (Amended) The semiconductor device according to claim 1, wherein the external connection terminal has an exposed portion exposed to the outside of the protective resin.

*such  
A2*

7. (Amended) A semiconductor device, comprising:  
a board;  
a semiconductor chip joined to the board in a state where its active surface is opposite to the board and its inactive surface which is a surface on the opposite side of the active surface is exposed; and  
an external connecting terminal electrically connected to the active surface of the semiconductor chip and projecting therefrom.

### **REMARKS**

Claims 1-17 are pending in the application. By this Amendment, claims 1, 2 and 7 are amended. Claims 10-17 stand withdrawn from consideration.

The Office Action indicates that the title of the invention is not descriptive. The title of the invention is changed in the manner above. It is respectfully submitted that the changed title of the invention is now descriptive.

Claims 1-9 are rejected under 35 U.S.C. §102(a) as anticipated by Lum (U.S. Patent No. 5,959,462). The rejection is respectfully traversed.

Lum discloses a test structure for burn-in testing on an entire semiconductor wafer. The test structure is illustrated in Figure 7 of Lum which has a signal distribution film 14, dies 28-34 with each bonded to the signal distribution film 14 via bumps 26 and an underfill material 36 filled in the gaps between the dies 28-34. A back support wafer 39 is adhered to be in active surfaces of the dies 28-34 by a die attach compound 38.

As shown in Figure 2 of Lum, conductive portions 22 are exposed from the signal distribution film 14. When testing a product wafer 44, contacts 46 on the product wafer

44 are pressed against the conductive portions 22, thereby testing the product wafer 44. See Figure 8 in Lum.

Claim 1 is directed to a semiconductor device that includes a semiconductor chip and a protective resin covering a sidewall of the semiconductor chip. Claim 1 also recites that the protective resin has a surface formed that so as to be flush with an inactive surface of the semiconductor chip which is a surface on the opposite side of an active surface of the semiconductor chip.

Claims 7 is directed to a semiconductor device that includes a board and a semiconductor chip. Claims 7 recites that the semiconductor chip is joined to the board in a state where its active surface is opposite to the board and its inactive surface which is a surface on the opposite side of the active surface is exposed.

Both claims 1 and 7 recite that the semiconductor devices thereof include an external connecting terminal electrically connected to the active surface of the semiconductor chip and projects therefrom.

It is respectfully submitted that the rejection is improper because the applied art fails to teach each element of claims 1 and 7. Specifically, the applied art fails to teach an external connecting terminal that is electrically connected to an active surface of a semiconductor chip and projects therefrom. By contrast, the contacts 46 shown in Figure 8 of Lum are provided on the product wafer 44 and, therefore, the test structure 50 has no external connecting terminal projecting from the surface thereof. Thus, for at least this reason, claims 1 and 7 are allowable over the applied art.

Claims 2-6 depend from claim 1 and include all of the features of claim 1. Claims 8 and 9 depend from claim 7 and include all of the features of claim 7. Thus, the dependent claims are allowable at least for the reason the independent claims are allowable as well as for the features they recite.

Withdrawal of the rejection is respectfully requested.

In view of the foregoing, reconsideration of the application and allowance of the pending claims are respectfully requested. Should the Examiner believe anything further is desirable in order to place the application in even better condition for


allowance, the Examiner is invited to contact Applicants' representative at the telephone number listed below.

In the event this paper is not considered to be timely filed, the Applicants respectfully petition for an appropriate extension of time. Any fees for such an extension, together with any additional fees that may be due with respect to this paper, may be charged to counsel's Deposit Account No.18-0013.

Respectfully submitted,

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By:

  
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Enclosure(s):      Marked-Up Version of Amended Claims  
                            Petition for Extension of Time (one month)

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**MARKED-UP VERSION OF AMENDED CLAIMS**

1. (Amended) A semiconductor device, comprising:  
a semiconductor chip; [and]  
protective resin covering a sidewall of the semiconductor chip and having  
a surface formed so as to be flush with an inactive surface of the semiconductor chip  
which is a surface on the opposite side of an active surface of the semiconductor chip;  
and  
an external connecting terminal electrically connected to the active  
surface of the semiconductor chip and projecting therefrom.
  
2. (Amended) The semiconductor device according to claim 1, [further  
comprising  
an] wherein the external connection terminal [electrically connected to the  
active surface of the semiconductor chip and having] has an exposed portion exposed  
to the outside of the protective resin.
  
7. (Amended) A semiconductor device, comprising:  
a board; [and]  
a semiconductor chip joined to the board in a state where its active  
surface is opposite to the board and its inactive surface which is a surface on the  
opposite side of the active surface is exposed; and  
an external connecting terminal electrically connected to the active  
surface of the semiconductor chip and projecting therefrom.